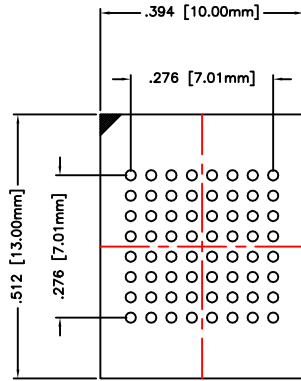


**PIN SPECIFICATIONS:**  
 MATERIAL: BRASS ALLOY 360 1/2 HARD PER QQ-B-828  
 FINISH: 10µ GOLD OVER 100µ NICKEL MIL-G-45204  
 ELECTRICAL PERFORMANCE TESTS IAW MIL-STD-202 OR 1344 METHODS:  
 MAX VOLTAGE: 50 VAC/80 VDC  
 MAX CURRENT: 1 AMP  
 CONTACT RES: .01Ω MAX .01 AMPS/5VDC  
 INSULATION RESISTANCE: @500 VDC: 5000 MEGOHMS MIN.  
 CAPACITANCE: 1pf MAX  
 SELF INDUCTANCE: 2nH MAX.

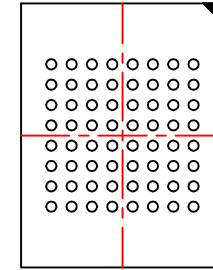
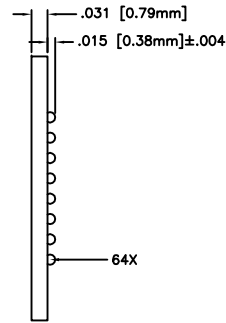
**MATERIAL SPECIFICATIONS:**  
 STANDARD MATERIAL:  
 GLASS EPOXY FR-4, IPC-4101/24,  
 MIL-S-13949/04-GF/GFGL  
 94V-0, CONTINUOUS USE TEMP 150C,  
 HEAT DEFLECTION TEMP(@264 PSI)175C  
 SOLDER BALL: 020# Sn96.5/Ag3.0/Cu.5,  
 Solder Melting Temperature 218.5°C

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
---	A	NEW RELEASE	10/27/09	

TOP VIEW



BOTTOM VIEW



NOTES:

- ADAPTER TO SOLDER ONTO TARGET BOARD USING HIGHER TEMP PROFILE.
- BGA CHIP TO SOLDER TO TOP OF ADAPTER USING NORMAL EUTECTIC PROFILE.

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CUSTOM BGA INTERPOSER FOR  
 64 BGA. FLIPS SIGNALS. (MIRROR IMAGE)

DRAWN BY: ANDREW MONTOYA	SIZE	FSCM NO.	DWG NO. CA064-0811-FLP	REV A
CHECKED: MIKE OIDEM	SCALE 2:1	DATE : 10/27/09	SHEET	